

December 2008

# **SuperFET**™

# FCH20N60 / FCA20N60 / FCA20N60\_F109

### **600V N-Channel MOSFET**

### **Features**

- 650V @T<sub>J</sub> = 150°C
- Typ. Rds(on)=0.15Ω
- Ultra low gate charge (typ. Qg=55nC)
- Low effective output capacitance (typ. Coss.eff=110pF)
- 100% avalanche tested
- · RoHS Compliant



### **Description**

SuperFET<sup>TM</sup> is, Fairchild's proprietary, new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET is very suitable for various AC/DC power conversion in switching mode operation for system miniaturization and higher efficiency.



## **Absolute Maximum Ratings**

Symbol	Parameter		FCH20N60	FCA20N60	Unit	
V <sub>DSS</sub>	Drain-Source Voltage		600		V	
I <sub>D</sub>	Drain Current - Continuous ( $T_C = 25^{\circ}C$ ) - Continuous ( $T_C = 100^{\circ}C$ )			20 12.5		A A
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	6	0	Α
$V_{GSS}$	Gate-Source voltage		± 30		V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note		(Note 2)	690		mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	20		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note		(Note 1)	20.8		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns	
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C		208 1.67		W W/°C	
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		°C	

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.6	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		41.7	°C/W

# Package Marking and Ordering Information

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
FCH20N60	FCH20N60	TO-247	-	-	30
FCA20N60	FCA20N60	TO-3P	-	-	30
FCA20N60	FCA20N60_F109	TO-3PN	-	-	30

## **Electrical Characteristics** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Charac	teristics			Į	ļ	
BV <sub>DSS</sub> Drain-Source Breakdown Voltage		$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^{\circ}C$	600			V
		V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 150°C		650		V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C		0.6		V/°C
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V, I_{D} = 20A$		700		V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 480V, T <sub>C</sub> = 125°C			1 10	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$ , $V_{DS} = 0V$			-100	nA
On Charac	teristics				•	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A		0.15	0.19	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 10A (Note 4)		17		S
Dynamic C	haracteristics					
C <sub>iss</sub>	Input Capacitance $V_{DS} = 25V, V_{GS} = 0V,$			2370	3080	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0MHz		1280	1665	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			95		pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 480V, V_{GS} = 0V, f = 1.0MHz$		65	85	pF
C <sub>oss</sub> eff.	Effective Output Capacitance $V_{DS} = 0V$ to 400V, $V_{GS} = 0V$			165		pF
Switching	Characteristics				•	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 300V, I <sub>D</sub> = 20A		62	135	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25\Omega$		140	290	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			230	470	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		65	140	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 480V, I <sub>D</sub> = 20A		75	98	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10V		13.5	18	nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)		36		nC
Drain-Sour	ce Diode Characteristics and Maximum	n Ratings			1	
Maximum Continuous Drain-Source Diode Forward Current					20	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				60	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	1			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A		530		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s    (Note 4)$		10.5		μС

### NOTES:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2.  $I_{AS}$  = 10A,  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25 $^{\circ}C$
- 3. I\_{SD}  $\leq$  20A, di/dt  $\leq$  200A/µs, V\_{DD}  $\leq$  BV\_DSS, Starting T\_J = 25°C
- 4. Pulse Test: Pulse width  $\leq 300 \mu s, \ Duty \ Cycle \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

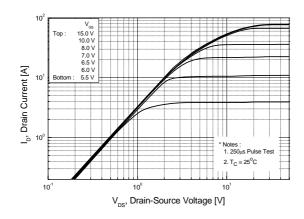


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

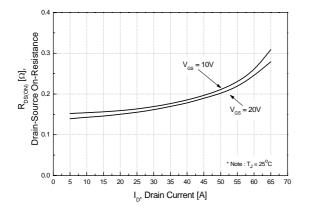


Figure 5. Capacitance Characteristics

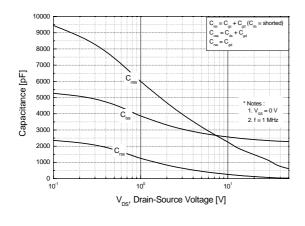


Figure 2. Transfer Characteristics

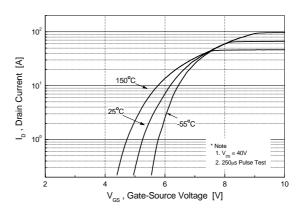


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

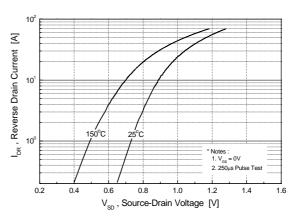
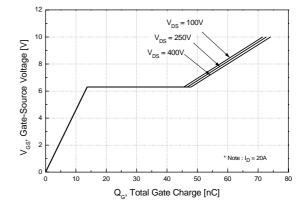


Figure 6. Gate Charge Characteristics



### **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

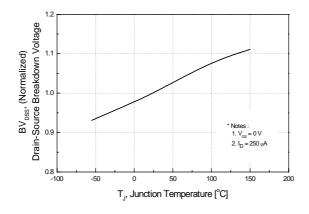


Figure 8. On-Resistance Variation vs. Temperature

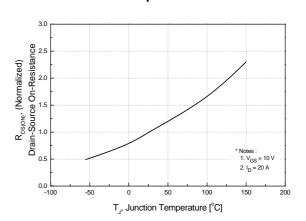


Figure 9. Maximum Safe Operating Area

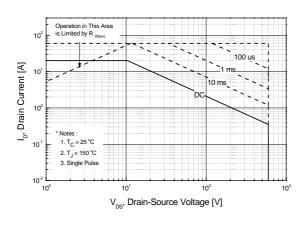


Figure 10. Maximum Drain Current vs. Case Temperature

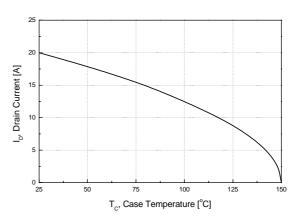
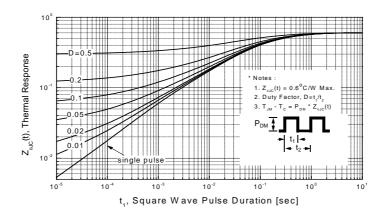
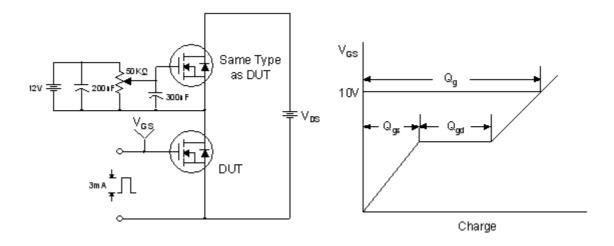


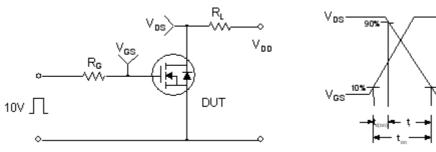
Figure 11. Transient Thermal Response Curve



### **Gate Charge Test Circuit & Waveform**

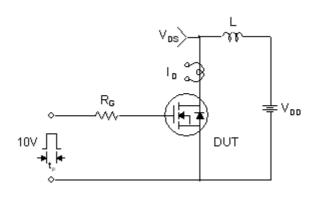


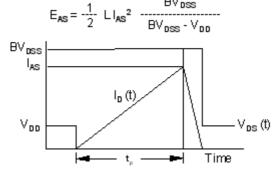
### **Resistive Switching Test Circuit & Waveforms**



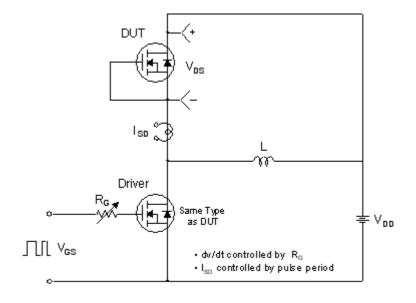
# V<sub>GS</sub> 10%

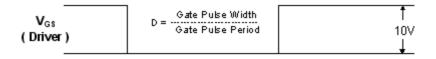
### **Unclamped Inductive Switching Test Circuit & Waveforms**

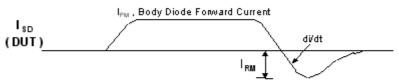




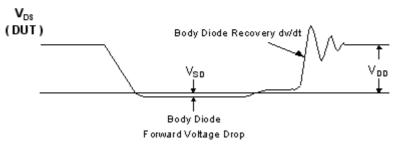
### Peak Diode Recovery dv/dt Test Circuit & Waveforms





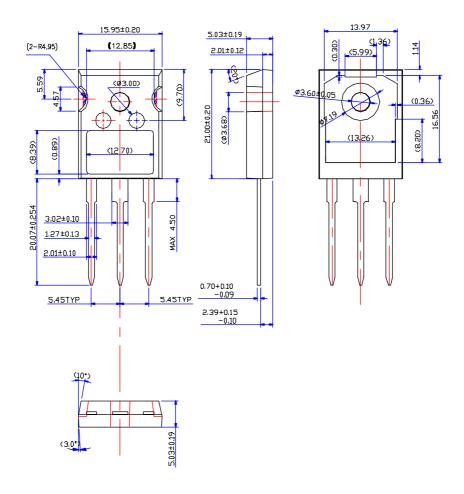


Body Diode Reverse Current



### **Mechanical Dimensions**

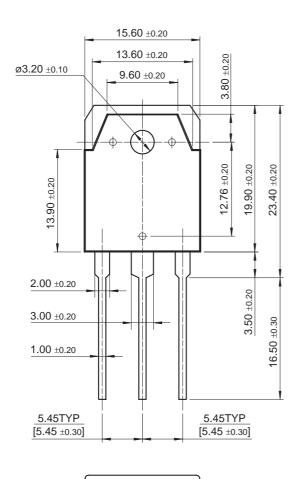
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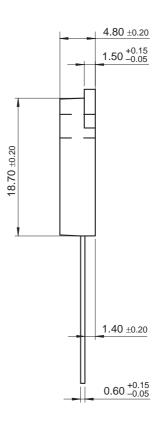


Dimensions in Millimeters

## **Mechanical Dimensions** (Continued)

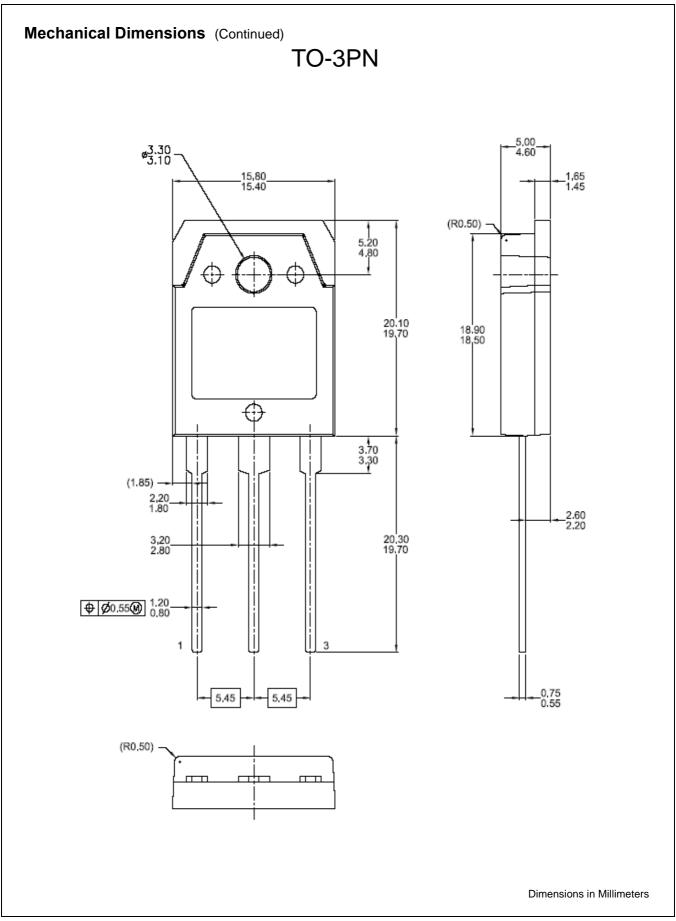
**TO-3P** 





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Dimensions in Millimeters







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